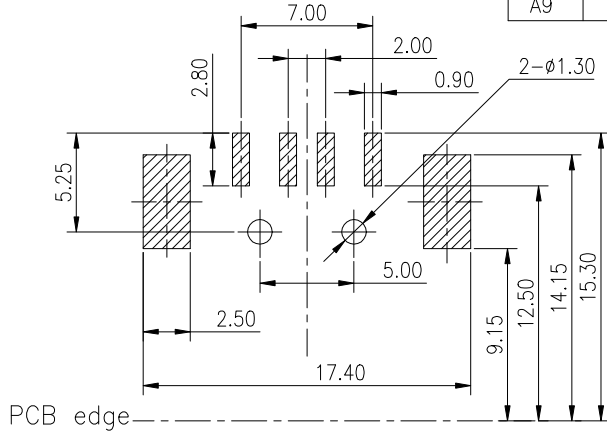
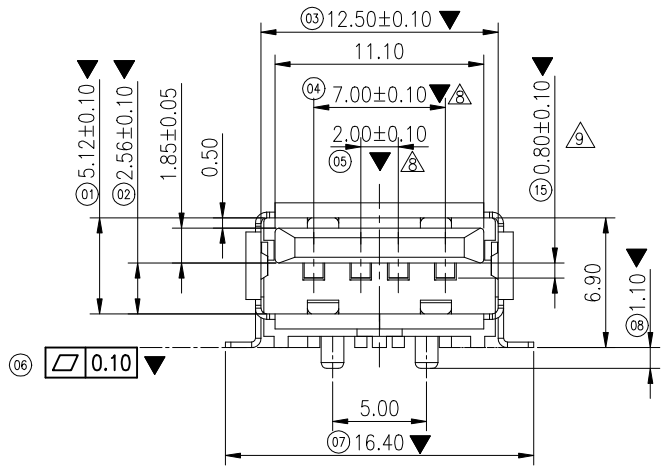


RoHS Compliant

REV.	ECN NO	LTR	DESCRIPTION	REVISER	DATE
A4	2011080201	△4	Rearrange the print to Customer's print.	Mac	2011.08.02
A5	2012100901	△5	Cha LCP to NYLON	Peng	2012.10.09
A6	2014061601	△6	Modify the structure of shell tails	Paul	2014.06.16
A7	2014080501	△7	Define the plating method in print.	Paul	2014.08.05
A8		△8	变更7.00±0.05为7.00±0.10, 变更2.00±0.05为2.00±0.10	HCZ	2022.05.09
A9		△9	变更弹高尺寸0.80±0.05为0.80±0.10	LEON	2023.04.14



RECOMMEND P.C.B LAYOUT

NOTES

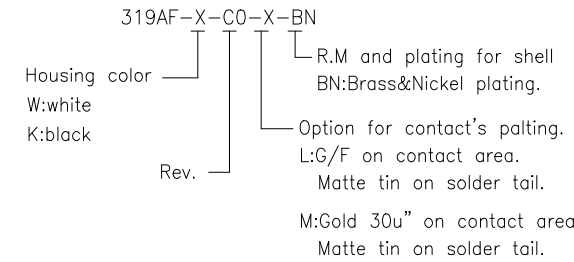
- ELECTRICAL:
  - CONTACT CURRENT RATING :1 AMPERES
  - DIELECTRIC WITHSTANDING VOLTAGE:AC 500V AT SEA LEVEL
  - INSULATION RESISTANCE:100MEGOHMS MIN
  - CONTACT RESISTANCE:30MILIOHMS MAX
  - OPERATING TEMPERATURE:-55°c TO +85°c
- MECHANICAL:
  - MATING FORE:3.57kgf MAX
  - UNMATING FORCE:1.02kgf MIN
- MATERIALS:
  - CONTACTS:BRONZE,GOLD/TIN PLATED
  - INSULATOR: PA9T
  - SHELL:BRASS,NICKEL PLATED
- PLATING:
  - CONTACT: GOLD ON CONTACT AREA
  - 100u" Min. Sn ON SOLDER TAIL .
  - 50u" Min. NICKEL PLATING ON UNDERPLATED

△ SHELL: 100u" Min NICKEL PLATING OVERALL.  
PASSIVATION TREATMENT CHEMICAL ADD 12.5% HOT WATER TO CLEAN

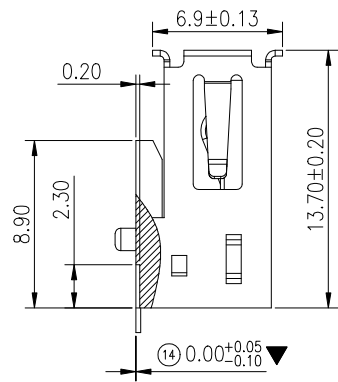
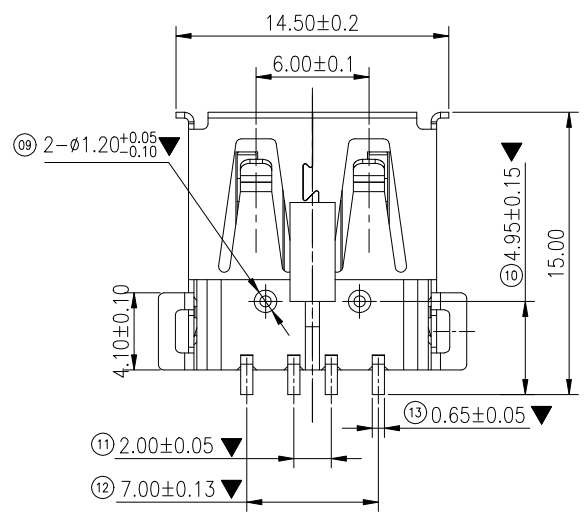
5.SOLDERABILITY TSET:  
△ REFERENCE TO STANDARD EIA-364-52A OR TYCO TEST SPEC 109-11  
THE FLUX TYPE:KESTER 145, NONACTIVATED ROSIN, TYPE R

6.THE DIMENSIONS WITH"▼"MARK ARE CRITICAL AND SHOULD BE CONTROLLED BY QC.

HOW TO ORDER



SAMTEC P/N: USB-A-S-XX-SM2-R-TR



图号 (DWG NO)	G-319-S2-27	单位 (UNIT):	MM	<b>显赫电子科技有限公司</b> XianHe Electronic Technology co., ltd.	
类别 (DWG TYPE)	ENG DWG	比例 (SCALE)	1:1		
版次 (REV):	A/9	页次 (PAGE):	1/1	TEL:0769-89138899 FAX:0769-89100950	
设计 (DESIGN)	Lizhenghua	未注公差	TOLERANCE UNSPECIFIED	品名 (ITEM NO)	USB A/F SMT
审核 (CHECKED)		X.X ± 0.15		料号 (PART NO)	319AFXC0XBN
核准 (APPROVED)		X.XX ± 0.10			
		X.XXX ± 0.05			
		X' ± 2			
		X.X' ± 1			